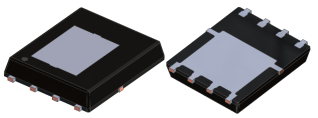
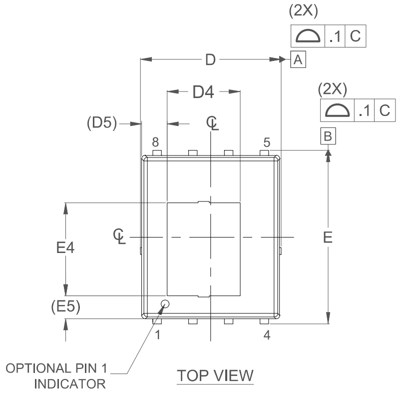
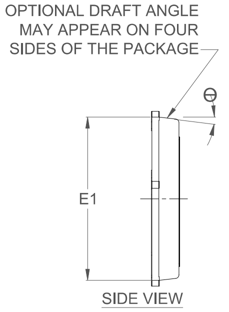


PQFN8 5X6, 1.27P
CASE 483BK
ISSUE A

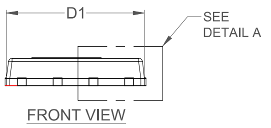
DATE 06 JUL 2021



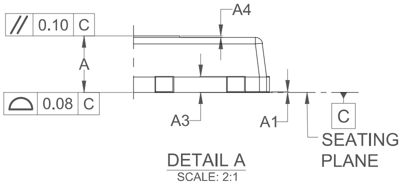
TOP VIEW



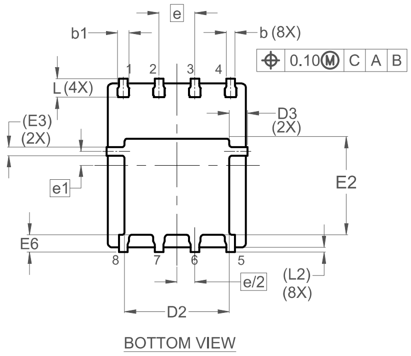
SIDE VIEW



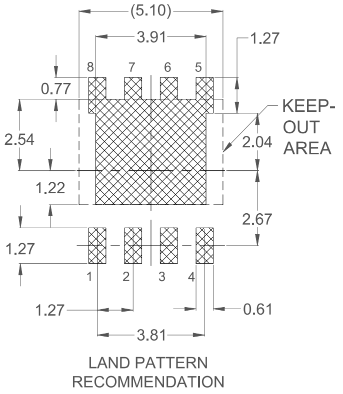
FRONT VIEW



DETAIL A
SCALE: 2:1



BOTTOM VIEW



LAND PATTERN RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

NOTES:

A) PACKAGE IS NOT FULLY COMPLIANT TO JEDEC MO-240, VARIATION AA.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	---	0.05
A3	0.23	0.28	0.33
A4	0.00	---	0.05
b	0.31	0.36	0.41
b1	0.36	0.41	0.46
D	4.90	5.00	5.10
D1	4.80	4.90	5.00
D2	3.62	3.72	3.82
D3	0.54	0.64	0.74
D4	2.60	2.70	2.80
D5		0.90 REF	
E	6.05	6.15	6.25
E1	5.70	5.80	5.90
E2	3.31	3.41	3.51
E3	0.25	0.30	0.35
E4	3.30	3.40	3.50
E5		0.81REF	
E6	0.51	0.61	0.71
e		1.27 BSC	
e/2		0.635 BSC	
e1		0.49 BSC	
L	0.56	0.66	0.76
L2		0.175 REF	
Θ	0°	---	12°

DOCUMENT NUMBER:	**98AON13689G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**PQFN8 5X6, 1.27P**	**PAGE 1 OF 1**